

Product Specification For TFT MODULE

Model NO.: CNKT0400-20113A1

CUSTOMER NO.:

REVISION: V00

DAPPROVAL FOR SPECIFICATIONS AND SAMPLE

	APPROVED BY	DATE
CUSTOMER APPROVAL		

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Version	Date	Description
V00	2021-09-10	



1. Display Characteristics

Item	Specification	Unit	Note
LCD Size	4.0	inch	
Panel Type	IPS	-	
Resolution	480(RGB)*480	pixel	
Display Mode	TRANSMISSIVE,NORMALLY BLACK	-	
Display Number of Colors	65K	-	
Viewing Direction	ALL VIEWING	-	Note1
Module Size	84.6*84.6*3.62	mm	Note1
Weight	TBD	g	
Driver IC	ST7701S	-	
Interface	Comprehensive type Interface	-	

Note 1: Please refer to the mechanical drawing.

2.Pin Assignments

Symbol	I/O	Function	Note
Α	Р	Backlight Anode	
K	Р	Backlight Cathode	
VCC	Р	POWER SUPPLY 2.8V-3.3V	
IOVCC	Р	POWER SUPPLY 1.8V-3.3V	
SDO	0	Serial data output pin used for SPI interface.	
SDI	I	Serial data input bidirectional pin for SPI Interface.	
SCL_WR	I	Serial clock input for SPI interface.	
CS	I	A chip select signal.	
IM3	I	The System interface mode select.	
RESET	I	The external reset input - Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power.	
R0-R7			
G0-G7	I/O	DATA BUSS	
B0-B7			
DE	1	Data enable signal for RGB interface operation Low: access enabled High: access inhibited	
PCLK	I	Dot clock signal for RGB interface operation	
HS	I	Line synchronizing signal for RGB interface operation	
VS	I	Frame synchronizing signal for RGB interface operation	
GND(ID)	Р	Power Ground	
GND	Р	Power Ground	
CTP_VDD3.3V	Р	CTP Power Supply 2.8V-3.3V	
CTP_SCL	Р	CTP I2C Clock Signal	
	K VCC IOVCC SDO SDI SCL_WR CS IM3 RESET R0-R7 G0-G7 B0-B7 DE PCLK HS VS GND(ID) GND CTP_VDD3.3V	A P K P VCC P IOVCC P IOVCC P SDO O SDI I SCL_WR I CS I IM3 I RESET I R0-R7 G0-G7 I/O B0-B7 DE I PCLK I HS I VS I GND(ID) P GND P CTP_VDD3.3V P	A P Backlight Anode K P Backlight Cathode VCC P POWER SUPPLY 2.8V-3.3V IOVCC P POWER SUPPLY 1.8V-3.3V SDO O Serial data output pin used for SPI interface. SDI I Serial data input bidirectional pin for SPI Interface. SCL_WR I Serial clock input for SPI interface. CS I A chip select signal. IM3 I The System interface mode select. The external reset input - Initializes the chip with a low input. Be sure to execute a power-on reset after supplying power. RO-R7 GO-G7 I/O DATA BUSS BO-B7 DE I Data enable signal for RGB interface operation Low: access enabled High: access inhibited PCLK I Dot clock signal for RGB interface operation VS I Frame synchronizing signal for RGB interface operation VS I Frame synchronizing signal for RGB interface operation GND(ID) P Power Ground CTP_VDD3.3V P CTP Power Supply 2.8V-3.3V



43	CTP_SDA	I/O	CTP I2C Data in/output Signal	
44	CTP_INT	0	CTP Interrupt Signal	
45	CTP_RESET	1	CTP Reset Signal	
46	GND	Р	Power Ground	
47	GND	Р	Power Ground	
48	NC	-	-	
49	NC	-	-	
50	NC	-	-	

3. Absolute Maximum Ratings

- <u> </u>							
Item	Symbol	Min	Max	Unit			
Power supply	VDD	2.5	3.3	V			
Operation temperature	Тор	-20	70	°C			
Storage temperature	Tst	-30	80	°C			

4. Electrical Characteristics

DC CHARACTERISTICS (at Ta=25°C)

ltem	Symbol		Values	Unit	Note	
item	Symbol	Min.	Тур.	Max.	Unit	Note
Logic Supply Voltage	VDD	2.6	2.8	3.3	V	
Supply Voltage For Panel	VGH		16		V	
	VGL		-7			
	AVDD		10.4			
	VCOM		TBD			REF.3.6V
Input Logic High Voltage	VIH	0.7VDD	-	VDD	V	
Input Logic Low Voltage	VIL	0	-	0.3VDD	V	
Output Logic High Voltage	Vон	0.8VDD	-	VDD	V	
Output Logic Low Voltage	Vol	0	_	0.2VDD	V	

5.Backlight Characteristics (at Ta=25°C,RH=60%)

Item	Symbol	Min.	Тур.	Max.	Unit	Note
LED forward voltage	VF	11.6	12.8	14	V	IF=40*1mA
LED forward current	IF		40		mA	
LED power consumption	PLED		480		mW	Note1
Uniformity		60			%	IF=40mA



Connection mode	 1 series * 1 parallel			/	
LED life-time	 20000			Hrs	Note2

Note1.Calculator Value for reference: IF*VF = PLED

Note2. The LED Life-time define as the estimated time to 50% degradation of initial brightness at Ta=25 $^{\circ}$ C and IF=40mA. The LED lifetime could be decreased if operating IF is larger than 40mA

6.Optical Specifications

Item	Symbol	Condition	Min	Тур	Max	Unit	Note	
Response time	Ton+ Toff	Normal	-	30	40	ms	Note 4,5	
Contrast ratio	Cr	θ=Φ=0°	600	800	-	-	Note 1.5	
Surface Iuminance	Lv	θ=0°	200	300	-	cd/m^2	Note 2,5	
	θL	Left(CR>10)	-	80	-	deg		
Viewing angle range	θR	Right(CR>10)	-	80	-	deg	Note 5,6	
	θТ	Top(CR>10)	-	80	-	deg		
	θВ	Bottom(CR>10)	-	80	-	deg		
	Red x			0.624		-		
	Red y			0.329		-		
	Green x	θ=0°		0.288		-		
CIE (x, y)	Green y	Ø=0°	Тур	0.522	Тур	_	Note 3,5	
chromaticity	Blue x		-0.04	0.136	+0.04	_	INOIG 3,3	
	Blue y	1a-25 C		0.137		_		
	White x			0.302		_		
	White y			0.325		-		

Note1. Definition of contrast ratio

Contrast Ratio(CR) is defined mathematically by the following formula.

Contrast Ratio = Average Surface Luminance with all white pixels Average Surface Luminance with all black pixels

Note 2.Definition of surface luminance

Surface luminance is the LCD surface from the surface with all pixels displaying white.

Lv = Average Surface Luminance with all white pixels

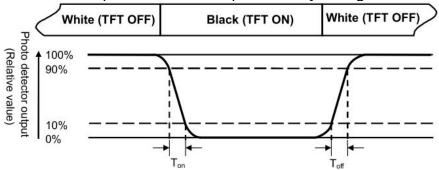
Note 3. Definition of color chromaticity (CIE1931)

CIE (x, y) chromaticity, The x,y value is determined by screen active area center position

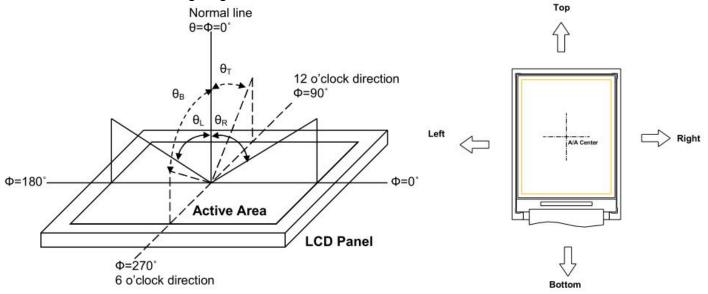
Note 4: Definition of response time



The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T on) is the time between photo detector output intensity changed from 90% to 10%, and fall time (T off) is the time between photo detector output intensity changed from 10% to 90%.



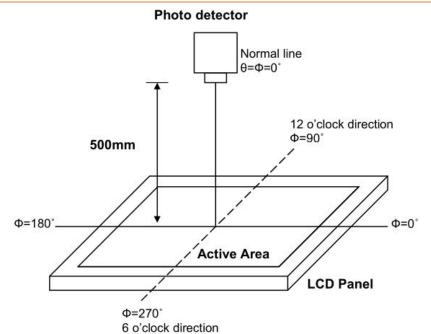
Note 5: Definition of viewing angle



Note 6: Definition of optical measurement system

The optical characteristics should be measured in a dark room with ambient temperature T a =+25. The optical properties are measured at the center point of the LCD screen after 5 minutes operation. (Equipment: Photo detector TOPCON BM-5A or BM-7 /Field of view: 1° /Height: 500mm.)





7.AC Characteristics

Refer to IC datasheet

8.Power sequenceRefer to IC datasheet

9. Reliability Test Conditions

J. Keliability Test Collations					
Test item	Test condition	Inspection after test			
High temperature storage	80±2°C/96 hours				
Low temperature storage	-30±2°C/96 hours				
High temperature operating	70±2°C/96 hours				
Low temperature operating	-20±2°C/96 hours	Note 1,2			
Temperature Shock	-20±2°C~25°C~70±2°C*10cycles (30min.) (5min.) (30min.)				
High Temperature Humidity Operation	60°C*90% RH/96 hours				



Vibration test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 2hours(Packing condition)	
Dropping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	
ESD test	Voltage : ±8KV, R:330Ω /C:150pF Air discharge, 10 time	

10. Handling Precautions

- 10.1. Safety
- 10.1.1.The liquid crystal in the LCD is poisonous.do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 10.2. Handling
- 10.2.1. The LCD and touch panel is made of plate glass.do not subject the panel to mechanical shock or to excessive force on its surface.
- 10.2.2.do not handle the product by holding the flexible pattern portion in order to assure the reliability
- 10.2.3. Transparency is an important factor for the touch panel. Please wear clear finger sacks, gloves and mask to protect the touch panel from finger print or stain and also hold the portion outside the view area when handling the touch panel.
- 10.2.4. Provide a space so that the panel does not come into contact with other components.
- 10.2.5. To protect the product from external force, put a covering lens (acrylic board or similar board) and keep an appropriate gap between them.
- 10.2.6. Transparent electrodes may be disconnected if the panel is used under environmental conditions where dew condensation occurs.
- 10.2.7. Property of semiconductor devices may be affected when they are exposed to light, possibly resulting in IC malfunctions.
- 10.2.8. To prevent such IC malfunctions, your design and mounting layout shall be done in the way that the IC is not exposed to light in actual use.
- 10.3. Static Electricity
- 10.3.1. Ground soldering iron tips, tools and testers when they are in operation.
- 10.3.2. Ground your body when handling the products.
- 10.3.3. Power on the LCD module before applying the voltage to the input terminals.
- 10.3.4.do not apply voltage which exceeds the absolute maximum rating.
- 10.3.5. Store the products in an anti-electrostatic bag or container.
- 10.4. Storage
- 10.4.1. Store the products in a dark place at +25°C±5°C with low humidity (65%RH or less).
- 10.4.2.do not store the products in an atmosphere containing organic solvents or corrosive gas.



- 10.5. Cleaning
- 10.5.1.do not wipe the touch panel with dry cloth, as it may cause scratch.
- 10.5.2. Wipe off the stain on the product by using soft cloth moistened with ethanol.do not allow ethanol to get in between the upper film and the bottom glass. It may cause peeling issue or defective operation.do not use any organic solvent or detergent other than ethanol.

11. Inspection Criterion

1.1 Description

This specification is made to be used as the standard acceptance/rejection criteria for TFT LCM Product.

11.1.1.Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

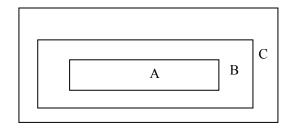
Major defect: AQL 0.65 Minor defect: AQL 1.5

11.1.2. Inspection condition

- •Viewing distance for cosmetic inspection is about 30±5cm with bare eyes, and under an environment 600~1000lux for visual inspection and 0~200lux for function test., all directions for inspecting the sample should be within 45°against perpendicular line. (Normal temperature 18~28°C and normal humidity 60±15%RH).
- Driving voltage

The Vop value from which the most optical contrast can be obtained near the specified Vop in the specification (Within ± 0.5 V of the typical value at 25°C.).

11.1.3. Definition of inspection zone in LCD



Zone A: character/Digit area

Zone B: viewing area except Zone A (Zone A+Zone B=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for



quality and assembly of customer's product.

11.2 Inspection criterion

11.2.1 Function defect

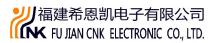
Items to be inspected	Inspection criterion	Classification of defects
All functional defects	 No display Display abnormally Missing vertical, horizontal segment Short circuit Back-light no lighting, flickering and abnormal lighting. obvious striation Current beyond specification value 	MA
Missing	Missing component	
Outline dimension	Overall outline dimension exceed the drawing is not allowed.	

11.2.2 LCD pixel defect (bad dot) (defect type:MI)

Checking item	Judgment criterion			
Item/LCD size	S ≤5.0 Inch	5.0 <s≤7.0 inch<="" th=""><th>7<s≤12.3 Inch</s≤12.3 </th></s≤7.0>	7 <s≤12.3 Inch</s≤12.3 	
Color bad dot-bright dot(R、G、B)	1	2	3	
two adjacent bright point	0	1	2	
three or more adjacent point	0	0	0	
total points for bad dot-bright dot	1	2	5	
Bad dot-dark dot	2	4	5	
two adjacent dark point	1	2	3	
three or more adjacent point	0	1	1	
total points for bad dot -dark dot	3	6	7	
patch bright dot		Invisible with ND5%, it is 0	OK.	

11.2.3 dot and line defect (defect type:MI)

Chaoking	Judg				
Checking item	Diameter(mm)\LCD Size	S ≤5.0	5 <s≤7< th=""><th>7<s≤12.3< th=""><th>Figure</th></s≤12.3<></th></s≤7<>	7 <s≤12.3< th=""><th>Figure</th></s≤12.3<>	Figure
ILEIII	Diameter (min)/LCD Size	Inch	Inch	Inch	
	D≤0.1	allowed	allowed	allowed	
Dot	0.1 <d≤0.2< td=""><td>4</td><td>allowed</td><td>allowed</td><td><u> </u></td></d≤0.2<>	4	allowed	allowed	<u> </u>
defect	0.2 <d≤0.3< td=""><td>0</td><td>5</td><td>6</td><td>\$ t b</td></d≤0.3<>	0	5	6	\$ t b
	0.3 <d≤0.5< td=""><td>0</td><td>0</td><td>0</td><td>· a ·</td></d≤0.5<>	0	0	0	· a ·



1						D (1)(0	
	D>0.5		0	0	0	D=(a+b)/2	
	the distance	e between th	e two defec	t dot:DS≥5m	m		
	Length(mm)	width(mm)	Judgment criterion			←	
line	disregard	W≤0.05	allowed	allowed	allowed	₩ w	
defect	L≤5	0.05< W≤0.1	4	5	7		
	L>5	W>0.1	0	0	0		
Concave	LCD Siz	e(mm)	Jud	dgment crit	terion		
point and	D≤	0.3	allowed	allowed	allowed		
air bubble	0.3<1	D≤1.0	3	4	5	\$ ь	
for	1.0<1	D≤1.5	1	2	3	i a	
polarizer	D>	1.5	0	0	0	D=(a+b)/2	
	Length (mm)	width (mm)	Ju	ıdgment cr			
	disregard	W≤0.05	allowed	allowed	allowed		
Fold mark、	1 <l≤5< td=""><td>0.05< W≤0.2</td><td>3</td><td>4</td><td>5</td><td>t w</td></l≤5<>	0.05< W≤0.2	3	4	5	t w	
	L>5	W>0.2	0	0	0		
linear scar for polarizer	condition,the defect is judge visible	ed with line ju	udge; 2.lft	he fold mark	and linear sca	with operating or for polarizer is obove judgment	

11.2.4 Corner and others crack for LCD (defect type:MI)

11.2.4 Corner and others cruck for LOD (defect type:mi)						
Checking item	Judgment criterion	Figure				
Electric conduction crack	X≤3.0mm,Y≤1/4w,Z≤t,N≤2	ZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZZ				
corner crack	X≤3.0mm,Y≤3.0mm,Z≤t,N≤3 Corner crack extended to ITO PIN,none allowed					



Checking item	Judgment criterion	Figure
surface crack	X≤1.5mm,Y≤1.0mm, Z≤t, N≤4	Z

11.2.5 Module Cosmetic Criteria (defect type:MI)

TI.Z.3 WIOGUIE OUSI	netic Officia (defect type:wii)
Item	Judgment Criterion
Difference in Spec.	None allowed
Pattern peeling	No substrate pattern peeling and floating
	No soldering missing
Coldoring defeate	No soldering bridge
Soldering defects	No cold soldering
	Notes:detail judgment referring to IPC-A-610 grade II
Resist flaw on	visible copper foil (0.5mm or more) on substrate pattern, none
Printed Circuit	allowed
Boards	
Accretion of metallic	No accretion of metallic foreign matters (Not exceed 0.2mm)
Foreign matter	
Stain	No stain to spoil cosmetic badly
Plate discoloring No plate fading, rusting and discoloring	
Newton ring	Referring to limited sample
Mura	Invisible with 5%ND,allowed
Light leaks	Referring to limited sample

11.2.6 Module Cosmetic Criteria

Increation			t level	Inspection
Inspection items	Inspection content	MAJ	MIN	Methods
items				and Tools
	The PIN cannot be broken.	√		
	Fold marks: Not in V" shape			
	Pin/line: concave, convex, skewed not to exceed		$\sqrt{}$	Inspection
	1/3 of width		V	with naked
FPC	Double-sided adhesive tape cannot fall off/skew		\checkmark	
_	Oxidation on pins (PAD) is not allowed		\checkmark	eyes
segment	open circuit /short circuit is not allowed on line	√		Standard
	Line / line: non-conductive sundries must not			card
	cross two lines, conductive sundries according to		\checkmark	Magnifier
	convex / concave judgment			
	The PAD on the product do not warp, deform or		$\sqrt{}$	



	fall off			
	Scratch: Scratch is not allowed on the film		1	
	Cover film: the sticker offset must not exceed the		√	
	drawing requirements			
	Bubbles: Bubbles must not span 2 lines and must not exceed 2		√	
	Stratification: product is not layered	$\sqrt{}$		
	Screen printing: screen printing should be clear,		1	
	not duplicate, missing or wrong		V	
	Guide pin indispensable/unbroken			
	No surface breakage/crack	$\sqrt{}$		
Back-light	Reflex tape/ FPC not dropped		√	
	The double-sided glue on the light guide plate must not be removed		√	
	Solder not melted			
SMT	Component standing or solder joint and end face disengage	$\sqrt{}$		
	Tin beads: removable tin beads not available,			
segment	non-removable tin beads not exceeding 0.2 MM			
	in diameter		'	
	in diameter		1	
	Line			
	Broken circuit or short circuit not allowed	$\sqrt{}$		
	2.Line damage or residual copper no more than	,		
	1/3 W			
	Scratch on the surface			
	1. scratch copper, reject			
	2. copper single line (not covered with green		\ \ \	Visual
CMT	paint)>1 mm, reject			
SMT	3. No more than 2 lines and exposed copper			Standard
segment	Part error			card
	1. Part specification, material number failed to			Magnifier
	match original part data ,reject 2. missing /multiple parts: no missing or multiple	$\sqrt{}$		
	parts on the circuit board	V		
	3. reverse: no positive and negative wrong			
	welding of parts on circuit board			
	Tin on board		,	
	1.Tin in front of 1/2 Lead, reject		\	
	TITLE TOTAL OF THE LOUIS, TOJOOL		L	

	TREE TO JUNE CON LELECTRONIC CO., LID.			
	2. products have hot pressing process, its gold finger (pressing area) tin, reject			
	Empty welding: welding surface and pad are not joint	√		
	No tin tip / crack or virtual welding		1	
	No white powder residue		1	
	Component offset			
	1.B≥1/2≥•L 2.A≥2/3•W			
	A W		V	
	3.A≥ 2/3•W B≥ 1/2•L 4.t≥ 1/2*T Reference 1,2 T			
SMT segment	Solder height is higher than solder foot 1.25 H (gull airfoil), reject Solder height is higher than surface (round type), reject		√	Visual Standard card Magnifier



	Gull airfoil: Solder height less than solder foot 1/3 H, or the solder pad less than 70% tin, reject			
	Cylindrical type: solder height less than surface 1/4 H or the solder pad less than 70% tin, reject	\checkmark		
	<1/4 H NG 70% NG</td <td></td> <td></td> <td></td>			
	Connectors (including: card cover) are not broken or dropped	V		
	Board warping: the gap between the PCB and the plane is not greater than 1/100 of the length (if no special requirements, according to this standard)		√	
	SI/UV adhesive coating must not have obvious		√	Visual Magnifier
	concave and convex		,	
	SI/UV glue not coated/ dropped or not fit in size		√	
Other	No glue in non-coating areas		1	
34.16.	Print position / font / text not in accordance with requirements		√	Magrilloi
	Easy to tear film color / position not in accordance with requirements		√	
Incoming, process, ROSH process control, check for conformity				
Packaging and marking of the product are clear and correspond		.1		
to the report		√	Visual	Visual
The relevant information provided to the customer is complete When the customer has a request		V		



11.2.7 structure, packaging inspection:

Inspection items	Inspection criterion	Defect level		Inspection Methods
		MAJ	MIN	and Tools
Structure segment	The structure does not conform to the drawing size	√		Visual
	Packaging material compliance	V		
	Packing Type Compliance	√		
	Tray or not	√		
	Packing Quantity Compliance	1		
Packing	Product packaging (placement) direction meets the requirements	√		
	Cartons damaged/deformed		√	
	Labels are required on inner/external packing cases (content: model, date, etc)	√		

Remarks:

- 1. above all structural dimensions per batch sampling quantity of 10 PCS, bad is not qualified.
- 2. environmental protection requirements:product inspection
- 2.1 Incoming, process, ROSH process control, check for conformity;2.2 Packaging and marking of the product are clear and correspond to the report
- 2.3 The relevant information provided to the customer is complete When the customer has a request

12. Mechanical Drawing

